## **IN THE CLAIMS:**

1. (Currently Amended) A manufacturing method of a display device <u>comprising</u> including the step of:

forming a wiring by partially <u>forming etching</u> a conductor film over a substrate by <u>use of discharging a reactive gas from a plasma treatment means having <u>one set of electrodes</u> an <u>electrode</u> for generating plasma at a pressure of 5 to 800 Torr.</u>

2. (Currently Amended) A manufacturing method of a display device <u>comprising</u> including the step of:

forming a wiring by partially <u>forming etching</u> a conductor film over a substrate by <u>use of discharging a reactive gas from a plasma treatment means having a plurality of <u>sets of</u> electrodes for generating plasma at a pressure of 5 to 800 Torr.</u>

3. (Canceled)

4. (Currently Amended) A manufacturing method of a display device comprising the steps of:

partially forming a conductor film over a substrate at a pressure of 5 to 800 Torr by use of first plasma treatment means having a plurality of electrodes;

forming a resist mask over [[on]] the conductor film; and

partially etching the conductor film at a pressure of 5 to 800 Torr by use of discharging a reactive gas from a second plasma treatment means having one set of electrodes with the resist mask as a mask and forming a wiring.

5. (Currently Amended) A manufacturing method of a display device comprising the steps of:

partially forming a conductor film over a substrate at a pressure of 5 to 800 Torr by use of first plasma treatment means;

forming a resist mask over [[on]] the conductor film; and

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partially etching the conductor film at a pressure of 5 to 800 Torr by use of

discharging a reactive gas from a second plasma treatment means having a plurality of sets of

electrodes with the resist mask as a mask and forming a wiring.

6. (Currently Amended) The manufacturing method of the display device according

to any of claims 1, 2, 4 and 5 1 to 5, wherein the substrate has a size of 1,000 x 1,200 mm<sup>2</sup> or

more.

7. (Currently Amended) The manufacturing method of the display device according

to any of claims 1, 2, 4 and 5 1 to 5, wherein the plasma treatment means scans the substrate

in one direction.

8. (Currently Amended) The manufacturing method of the display device according

to any of claims 1, 2, 4 and 5 1 to 5, wherein the plasma treatment means alternately scans the

substrate in a row direction and in a column direction.

9. (Currently Amended) The manufacturing method of the display device according

to any of claims 4 and 5 3 to 5, wherein the resist mask is formed by use of liquid droplet

jetting means.

10. – 11. (Canceled)